

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Yan Xun Xue	08/31/2012
RECEIVING PARTY DATA	
Name:	Alpha and Omega Semiconductor Incorporated
Street Address:	475 Oakmead Pkwy,
City:	Sunnyvale
State/Country:	CALIFORNIA
Postal Code:	94085
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13602144
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ATTORNEY DOCKET NUMBER:	APOM077
NAME OF SUBMITTER:	Chein-Hwa Tsao
Total Attachments: 1 source=APOM077Assignment#page1.tif	

OP \$40.00 13602144

From:

Name: Yan Xun Xue

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TEL: 408-830-9742, FAX: 408-830-9757

To:

US Patent & Trademark Office

Assignment Recordation Services

P.O. Box 1450

Alexandria, VA 22313-1450, USA

Subject: Assignment Letter

Dear Sir/madam:

With this letter, we hereby assign the following subject US utility patent application entitled:

WAFER LEVEL CHIP SCALE PACKAGE WITH THICK BOTTOM METAL EXPOSED
AND PREPARATION METHOD THEREOF

Inventor: Yan Xun Xue

to the following receiving party:

Name: Alpha and Omega Semiconductor Incorporated

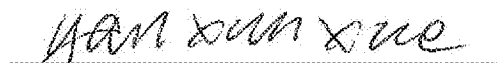
Officer name: Mike F. Chang

Title: CEO

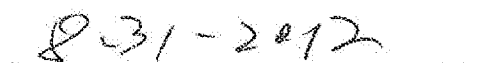
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Signature and Date of Conveying Party:



Yan Xun Xue



Date